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(54) **EMBEDDED TRANSISTOR DEVICES**

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(57) **ABSTRACT**

An embedded component stack includes a first metal layer, a first dielectric layer disposed on the first metal layer, a second metal layer disposed on the first dielectric layer, a first component disposed and embedded entirely within the first dielectric layer and entirely between the first metal layer and the second metal layer, a second dielectric layer disposed on the second metal layer, and a second component disposed on or embedded entirely within the second dielectric layer. The first and second components can be bare, unpackaged dies disposed over the metal layers by micro-transfer printing. The metal layers can be patterned and can be electrically connected to the components. The first component can be rotated with respect to the second component. Multiple components can be embedded in one or more of the dielectric layers.